

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application

CLAIMS LISTING:

1-20 (Cancelled)

21. (Currently Amended) A method for facilitating the transfer of heat from an electronic component to a heat sink across an interface therebetween, the method comprising the steps:

- a) providing a thermal interface wafer interposable between said electronic component and said heat sink, said wafer comprising at least one elongate vertically-oriented strip ~~planar~~ substrate having first and second surfaces, said substrate having at least one layer of a phase-change ~~conformable~~, heat-conductive material formed upon a respective surface thereof, said heat-conductive material being formulated to enhance the heat transfer from said electronic component to said heat sink;
- b) interposing the thermal interface wafer of step a) between said electronic component and said heat sink such that the ~~planar~~ substrate of such wafer assumes a substantially perpendicular orientation relative said electronic component and said heat sink; ~~and~~
- c) compressively engaging said electronic component to said heat sink with said thermal interface disposed therebetween; and

d) operating said electronic component such that heat is generated thereby, said heat being sufficient to cause said phase-change, heat-conductive material in step a) to transition from a solid phase to a liquid phase.

22. (Original) The method for facilitating the transfer of heat of Claim 21 wherein in step (a), said substrate comprises a thermally conductive metal foil.

23. (Original) The method of Claim 22 wherein said foil is formed from the group consisting of copper, gold, silver and aluminum.

24. (Currently Amended) The method of Claim 21 wherein said layer of conformable, heat-conducting material is formulated to have a melting point of approximately 51°C ~~or higher~~.

25-36 (Cancelled)

37. (New) The method of Claim 21 wherein in step a), said thermal interface wafer has a generally rectangular configuration.

38. (New) The method of Claim 21 wherein in step a), said thermal interface wafer has a generally square configuration.